FIFTEEN OUTPUT DIFFERENTIAL ZBUFFER FOR PCIE GEN2/3 AND QPI 9ZX21501B

Description

The 9ZX21501B is a 15 output version of the Intel DB1900Z Differential Buffer suitable for PCIe Gen3 or QPI applications. The part is backwards compatible to PCIe Gen1 and Gen2. An adjustable external feedback path allows the user to eliminate trace delays from their design while maintaining low drift for critical QPI applications. In bypass mode, the 9ZX21501B can provide outputs up to 400MHz.

Recommended Application

15-output PCIe Gen3/QPI buffer with adjustable feedback for Romley platforms

Output Features

- 15 - 0.7V current mode differential HCSL output pairs

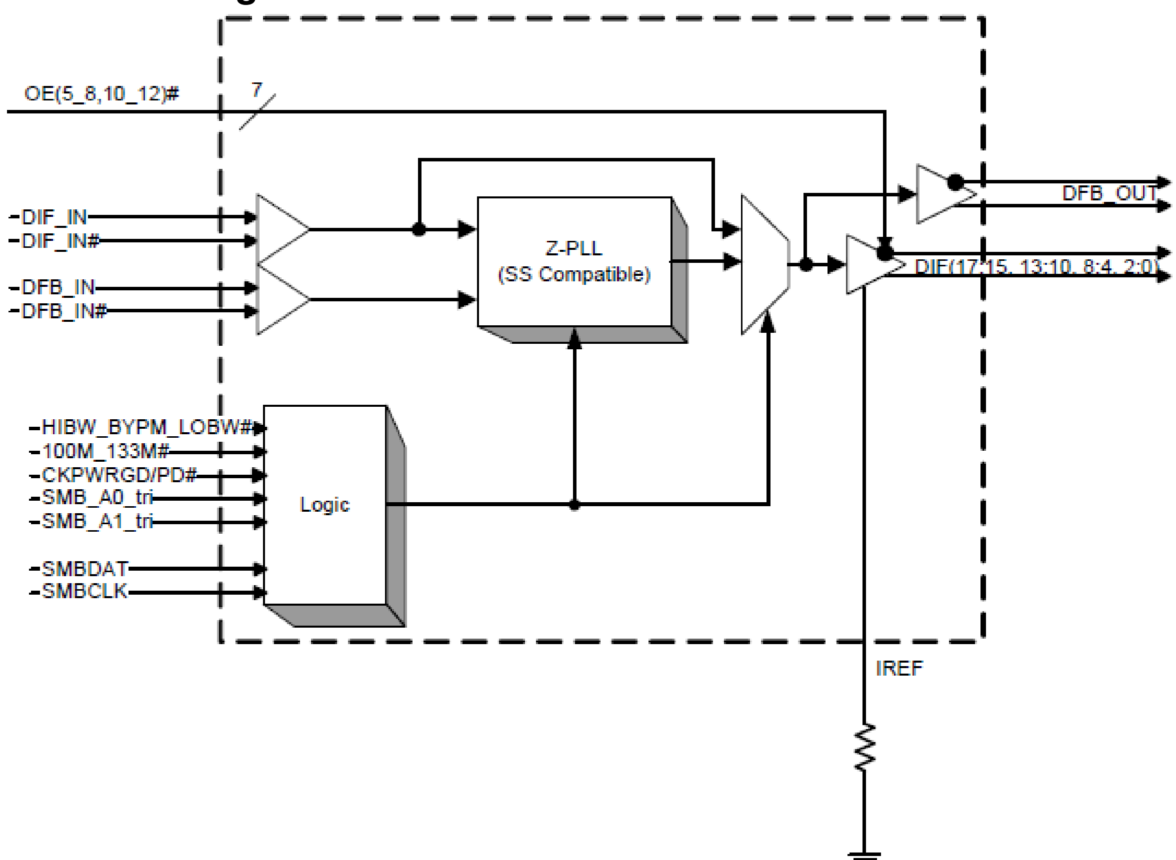
Features/Benefits

- External feedback path; adjustable input-to-output delay
- 9 Selectable SMBus addresses; multiple devices can share same SMBus segment
- 7 dedicated OE# pins; hardware control of outputs
- PLL or bypass mode; PLL can dejitter incoming clock
- Selectable PLL BW; minimizes jitter peaking in downstream PLL's
- Spread spectrum compatible; tracks spreading input clock for EMI reduction
- SMBus Interface; unused outputs can be disabled
- 100MHz & 133.33MHz PLL mode; legacy QPI support
- Undriven differential outputs in Power Down mode for maximum power savings

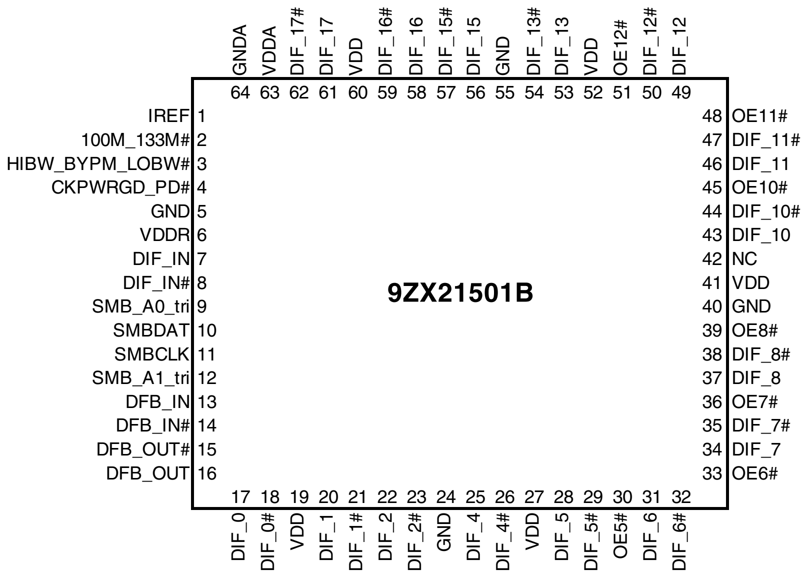
Key Specifications

- Cycle-to-cycle jitter: <50ps
- Output-to-output skew: <65ps
- Input-to-output delay: User adjustable
- Input-to-output delay variation: <50ps
- Phase jitter: PCIe Gen3 <1ps rms
- Phase jitter: QPI 9.6GB/s <0.2ps rms

Functional Block Diagram



Pin Configuration



Power Management Table

Inputs		Control Bits/Pins				Outputs	PLL State
CKPWRGD•/PD#	DIF_IN/ DIF_IN#	SMBus EN bit	OE# Pin	DIF(5:8,10:12)/ DIF(5:8,10:12)#	Other DIF/ DIF#	DFB_OUT/ DFB_OUT#	
0	X	X	X	Hi-Z[1]	Hi-Z[1]	Hi-Z[1]	OFF
1	Running	0	X	Hi-Z[1]	Hi-Z[1]	Running	ON
		1	0	Running	Running	Running	ON
		1	1	Hi-Z[1]	Running	Running	ON

NOTE 1: Due to external pull down resistors, HI-Z results in Low/Low on the True/Complement outputs

Functionality at Power-up (PLL mode)

100M_133M#	DIF_IN (MHz)	DIF MHz
1	100.00	DIF_IN
0	133.33	DIF_IN

PLL Operating Mode

HiBW_BypM_LoBW#	MODE
Low	PLL Lo BW
Mid	Bypass
High	PLL Hi BW

NOTE: PLL is OFF in Bypass Mode

PLL Operating Mode Readback Table

HiBW_BypM_LoBW#	Byte0, bit 7	Byte 0, bit 6
Low (Low BW)	0	0
Mid (Bypass)	0	1
High (High BW)	1	1

Tri-Level Input Thresholds

Level	Voltage
Low	<0.8V
Mid	1.2<Vin<1.8V
High	Vin > 2.2V

Power Connections

Pin Number		Description
VDD	GND	
63	64	Analog PLL
6	5	Input Circuit
19, 27, 41, 52, 60	24, 40, 55	DIF clocks

SMBus Addressing

Pin		SMBus Address
SMB_A1_tri	SMB_A0_tri	(Rd/Wrt bit = 0)
0	0	D8
0	M	DA
0	1	DE
M	0	C2
M	M	C4
M	1	C6
1	0	CA
1	M	CC
1	1	CE

Pin Descriptions

PIN #	PIN NAME	TYPE	DESCRIPTION
1	IREF	OUT	This pin establishes the reference for the differential current-mode output pairs. It requires a fixed precision resistor to ground. 475ohm is the standard value for 100ohm differential impedance. Other impedances require different values. See data sheet.
2	100M_133M#	IN	3.3V Input to select operating frequency See Functionality Table for Definition
3	HIBW_BYPM_LOBW#	IN	Trilevel input to select High BW, Bypass or Low BW mode. See PLL Operating Mode Table for Details.
4	CKPWRGD_PD#	IN	Notifies device to sample latched inputs and start up on first high assertion, or exit Power Down Mode on subsequent assertions. Low enters Power Down Mode.
5	GND	PWR	Ground pin.
6	VDDR	PWR	3.3V power for differential input clock (receiver). This VDD should be treated as an analog power rail and filtered appropriately.
7	DIF_IN	IN	0.7 V Differential TRUE input
8	DIF_IN#	IN	0.7 V Differential Complementary Input
9	SMB_A0_tri	IN	SMBus address bit. This is a tri-level input that works in conjunction with the SMB_A1 to decode 1 of 9 SMBus Addresses.
10	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant
11	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant
12	SMB_A1_tri	IN	SMBus address bit. This is a tri-level input that works in conjunction with the SMB_A0 to decode 1 of 9 SMBus Addresses.
13	DFB_IN	IN	True half of differential feedback input, provides feedback signal to the PLL for synchronization with the input clock to elimate phase error.
14	DFB_IN#	IN	Complementary half of differential feedback input, provides feedback signal to the PLL for synchronization with input clock to elimate phase error.
15	DFB_OUT#	OUT	Complementary half of differential feedback output, provides feedback signal to the PLL for synchronization with input clock to eliminate phase error.
16	DFB_OUT	OUT	True half of differential feedback output, provides feedback signal to the PLL for synchronization with the input clock to eliminate phase error.
17	DIF_0	OUT	0.7V differential true clock output
18	DIF_0#	OUT	0.7V differential Complementary clock output
19	VDD	PWR	Power supply, nominal 3.3V
20	DIF_1	OUT	0.7V differential true clock output
21	DIF_1#	OUT	0.7V differential Complementary clock output
22	DIF_2	OUT	0.7V differential true clock output
23	DIF_2#	OUT	0.7V differential Complementary clock output
24	GND	PWR	Ground pin.
25	DIF_4	OUT	0.7V differential true clock output
26	DIF_4#	OUT	0.7V differential Complementary clock output
27	VDD	PWR	Power supply, nominal 3.3V
28	DIF_5	OUT	0.7V differential true clock output
29	DIF_5#	OUT	0.7V differential Complementary clock output
30	OE5#	IN	Active low input for enabling DIF pair 5. 1 =disable outputs, 0 = enable outputs
31	DIF_6	OUT	0.7V differential true clock output
32	DIF_6#	OUT	0.7V differential Complementary clock output
33	OE6#	IN	Active low input for enabling DIF pair 6. 1 =disable outputs, 0 = enable outputs
34	DIF_7	OUT	0.7V differential true clock output
35	DIF_7#	OUT	0.7V differential Complementary clock output
36	OE7#	IN	Active low input for enabling DIF pair 7. 1 =disable outputs, 0 = enable outputs

Pin Descriptions (continued)

37	DIF_8	OUT	0.7V differential true clock output
38	DIF_8#	OUT	0.7V differential Complementary clock output
39	OE8#	IN	Active low input for enabling DIF pair 8. 1 =disable outputs, 0 = enable outputs
40	GND	PWR	Ground pin.
41	VDD	PWR	Power supply, nominal 3.3V
42	NC	N/A	No Connection.
43	DIF_10	OUT	0.7V differential true clock output
44	DIF_10#	OUT	0.7V differential Complementary clock output
45	OE10#	IN	Active low input for enabling DIF pair 10. 1 =disable outputs, 0 = enable outputs
46	DIF_11	OUT	0.7V differential true clock output
47	DIF_11#	OUT	0.7V differential Complementary clock output
48	OE11#	IN	Active low input for enabling DIF pair 11. 1 =disable outputs, 0 = enable outputs
49	DIF_12	OUT	0.7V differential true clock output
50	DIF_12#	OUT	0.7V differential Complementary clock output
51	OE12#	IN	Active low input for enabling DIF pair 12. 1 =disable outputs, 0 = enable outputs
52	VDD	PWR	Power supply, nominal 3.3V
53	DIF_13	OUT	0.7V differential true clock output
54	DIF_13#	OUT	0.7V differential Complementary clock output
55	GND	PWR	Ground pin.
56	DIF_15	OUT	0.7V differential true clock output
57	DIF_15#	OUT	0.7V differential Complementary clock output
58	DIF_16	OUT	0.7V differential true clock output
59	DIF_16#	OUT	0.7V differential Complementary clock output
60	VDD	PWR	Power supply, nominal 3.3V
61	DIF_17	OUT	0.7V differential true clock output
62	DIF_17#	OUT	0.7V differential Complementary clock output
63	VDDA	PWR	3.3V power for the PLL core.
64	GNDA	PWR	Ground pin for the PLL core.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9ZX21501B. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
3.3V Core Supply Voltage	VDDA				4.6	V	1,2
3.3V Logic Supply Voltage	VDD				4.6	V	1,2
Input Low Voltage	V_{IL}		GND-0.5			V	1
Input High Voltage	V_{IH}	Except for SMBus interface			V_{DD}+0.5V	V	1
Input High Voltage	V_{IHSMB}	SMBus clock and data pins			5.5V	V	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

[1]Guaranteed by design and characterization, not 100% tested in production.

[2] Operation under these conditions is neither implied nor guaranteed.

Electrical Characteristics–Clock Input Parameters

TA = $T_{COM;}$ Supply Voltage VDD/VDDA = 3.3 V +/-5%, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage - DIF_IN	V_{IHDIF}	Differential inputs (single-ended measurement)	600	750	1150	mV	1
Input Low Voltage - DIF_IN	V_{ILDIF}	Differential inputs (single-ended measurement)	V_{SS} - 300	0	300	mV	1
Input Common Mode Voltage - DIF_IN	V_{COM}	Common Mode Input Voltage	300		1000	mV	1
Input Amplitude - DIF_IN	V_{SWING}	Peak to Peak value	300		1450	mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I_{IN}	$V_{IN} = V_{DD}$, V_{IN} = GND	-5		5	uA	1
Input Duty Cycle	d_{tin}	Measurement from differential wavefrom	45		55	%	1
Input Jitter - Cycle to Cycle	J_{DIFIn}	Differential Measurement	0		125	ps	1

[1] Guaranteed by design and characterization, not 100% tested in production.

[2]Slew rate measured through +/-75mV window centered around differential zero

Electrical Characteristics–Input/Supply/Common Output Parameters

TA = $T_{COM;}$ Supply Voltage VDD/VDDA = 3.3 V +/-5%, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Ambient Operating Temperature	T_{COM}	Commmercial range	0		70	°C	1
Input High Voltage	V_{IH}	Single-ended inputs, except SMBus, low threshold and tri-level inputs	2		V_{DD} + 0.3	V	1
Input Low Voltage	V_{IL}	Single-ended inputs, except SMBus, low threshold and tri-level inputs	GND - 0.3		0.8	V	1
Input Current	I_{IN}	Single-ended inputs, V_{IN} = GND, V_{IN} = VDD	-5		5	uA	1
	I_{INP}	Single-ended inputs V_{IN} = 0 V; Inputs with internal pull-up resistors V_{IN} = VDD; Inputs with internal pull-down resistors	-200		200	uA	1
Input Frequency	F_{ibyp}	V_{DD} = 3.3 V, Bypass mode	33		400	MHz	2
	F_{ipll}	V_{DD} = 3.3 V, 100MHz PLL mode	90	100.00	105	MHz	2
	F_{ipll}	V_{DD} = 3.3 V, 133.33MHz PLL mode	120	133.33	140	MHz	2
Pin Inductance	L_{pin}				7	nH	1
Capacitance	C_{IN}	Logic Inputs, except DIF_IN	1.5		5	pF	1
	C_{INDIF_IN}	DIF_IN differential clock inputs	1.5		2.7	pF	1,4
	C_{OUT}	Output pin capacitance			6	pF	1
Clk Stabilization	T_{STAB}	From V_{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock			1.8	ms	1,2
Input SS Modulation Frequency	f_{MODIN}	Allowable Frequency (Triangular Modulation)	30		33	kHz	1
OE# Latency	$t_{LATOE\#}$	DIF start after OE# assertion DIF stop after OE# deassertion	4		12	clocks	1,3
Tdrive_PD#	t_{DRVPD}	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	t_F	Fall time of control inputs			5	ns	1,2
Trise	t_R	Rise time of control inputs			5	ns	1,2
SMBus Input Low Voltage	V_{ILSMB}				0.8	V	1
SMBus Input High Voltage	V_{IHSMB}		2.1		V_{DDSMB}	V	1
SMBus Output Low Voltage	V_{OLSMB}	@ I_{PULLUP}			0.4	V	1
SMBus Sink Current	I_{PULLUP}	@ V_{OL}	4			mA	1
Nominal Bus Voltage	V_{DDSMB}	3V to 5V +/- 10%	2.7		5.5	V	1
SCLK/SDATA Rise Time	t_{RSMB}	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t_{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f_{MAXSMB}	Maximum SMBus operating frequency			100	kHz	1,5

[1]Guaranteed by design and characterization, not 100% tested in production.

[2]Control input must be monotonic from 20% to 80% of input swing.

[3]Time from deassertion until outputs are >200 mV

[4] DIF_IN input

[5]The differential input clock must be running for the SMBus to be active

Electrical Characteristics–DIF 0.7V Current Mode Differential Outputs

TA = T_{COM}; Supply Voltage VDD/VDDA = 3.3 V +/-5%, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	Trf	Scope averaging on	1	2.5	4	V/ns	1, 2, 3
Slew rate matching	ΔTrf	Slew rate matching, Scope averaging on			20	%	1, 2, 4
Voltage High	VHigh	Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on)	660	750	850	mV	1
Voltage Low	VLow		-150		150		1
Max Voltage	Vmax	Measurement on single ended signal using absolute value. (Scope averaging off)			1150	mV	1
Min Voltage	Vmin		-300				1
Vswing	Vswing	Scope averaging off	300			mV	1, 2
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	250		550	mV	1, 5
Crossing Voltage (var)	Δ-Vcross	Scope averaging off			140	mV	1, 6

[1]Guaranteed by design and characterization, not 100% tested in production. IREF = VDD/(3xR_R). For R_R = 475Ω (1%), I_{REF} = 2.32mA. I_{OH} = 6 x I_{REF} and V_{OH} = 0.7V @ Z_O=50Ω (100Ω differential impedance).

[2] Measured from differential waveform

[3] Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

[4] Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

[5] Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

[6] The total variation of all Vcross measurements in any particular system. Note that this is a subset of V_cross_min/max (V_cross absolute) allowed. The intent is to limit Vcross induced modulation by setting V_cross_delta to be smaller than V_cross absolute.

Electrical Characteristics–Current Consumption

TA = T_{COM}; Supply Voltage VDD/VDDA = 3.3 V +/-5%, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	$I_{DD3.3OP}$	All outputs active @100MHz, C_L = Full load;		390	425	mA	1
Powerdown Current	$I_{DD3.3PDZ}$	All differential pairs tri-stated		5	15	mA	1

[1]Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics–Skew and Differential Jitter Parameters

TA = $T_{COM;}$ Supply Voltage VDD/VDDA = 3.3 V +/-5%, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
CLK_IN, DIF[x:0]	t_{SPO_PLL}	Input-to-Output Skew in PLL mode nominal value @ 25°C, 3.3V	-300	-200	-100	ps	1,2,4,5,8
CLK_IN, DIF[x:0]	t_{PD_BYP}	Input-to-Output Skew in Bypass mode nominal value @ 25°C, 3.3V	2.5	3.5	4.5	ns	1,2,3,5,8
CLK_IN, DIF[x:0]	t_{DSPO_PLL}	Input-to-Output Skew Varation in PLL mode across voltage and temperature	-50	0	50	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t_{DSPO_BYP}	Input-to-Output Skew Varation in Bypass mode across voltage and temperature	-250		250	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t_{DTE}	Random Differential Tracking error beween two 9ZX devices in Hi BW Mode		3	5	ps (rms)	1,2,3,5,8
CLK_IN, DIF[x:0]	t_{DSSTE}	Random Differential Spread Spectrum Tracking error beween two 9ZX devices in Hi BW Mode		15	75	ps	1,2,3,5,8
DIF{x:0]	t_{SKEW_ALL}	Output-to-Output Skew across all outputs (Common to Bypass and PLL mode)		45	65	ps	1,2,3,8
PLL Jitter Peaking	$j_{peak-hibw}$	LOBW#_BYPASS_HIBW = 1	0	1	2.5	dB	7,8
PLL Jitter Peaking	$j_{peak-lobw}$	LOBW#_BYPASS_HIBW = 0	0	1	2	dB	7,8
PLL Bandwidth	pll_{HIBW}	LOBW#_BYPASS_HIBW = 1	2	3	4	MHz	8,9
PLL Bandwidth	pll_{LOBW}	LOBW#_BYPASS_HIBW = 0	0.7	1	1.4	MHz	8,9
Duty Cycle	t_{DC}	Measured differentially, PLL Mode	45	50	55	%	1
Duty Cycle Distortion	t_{DCD}	Measured differentially, Bypass Mode @100MHz	-2	0	2	%	1,10
Jitter, Cycle to cycle	$t_{jcyc-cyc}$	PLL mode		24	50	ps	1,11
		Additive Jitter in Bypass Mode		20	50	ps	1,11

Notes for preceding table:

[1] Measured into fixed 2 pF load cap. Input to output skew is measured at the first output edge following the corresponding input.

[2] Measured from differential cross-point to differential cross-point. This parameter can be tuned with external feedback path, if present.

[3] All Bypass Mode Input-to-Output specs refer to the timing between an input edge and the specific output edge created by it.

[4] This parameter is deterministic for a given device

[5] Measured with scope averaging on to find mean value. DIF_IN slew rate must be matched to DIF output slew rate.

[6.] t is the period of the input clock

[7] Measured as maximum pass band gain. At frequencies within the loop BW, highest point of magnification is called PLL jitter peaking.

[8.] Guaranteed by design and characterization, not 100% tested in production.

[9] Measured at 3 db down or half power point.

[10] Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

[11] Measured from differential waveform

Electrical Characteristics–Phase Jitter Parameters

TA = $T_{COM;}$ Supply Voltage VDD/VDDA = 3.3 V +/-5%, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
Jitter, Phase	$t_{jphPCIeG1}$	PCIe Gen 1		36	86	ps (p-p)	1,2,3
	$t_{jphPCIeG2}$	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		1.2	3	ps (rms)	1,2
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		1.9	3.1	ps (rms)	1,2
	$t_{jphPCIeG3}$	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.5	1	ps (rms)	1,2,4
	t_{jphQPI_SMI}	QPI & SMI (100MHz or 133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.31	0.5	ps (rms)	1,5
		QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.21	0.3	ps (rms)	1,5
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.17	0.2	ps (rms)	1,5
Additive Phase Jitter, Bypass mode	$t_{jphPCIeG1}$	PCIe Gen 1		4	10	ps (p-p)	1,2,3
	$t_{jphPCIeG2}$	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.25	0.3	ps (rms)	1,2,6
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		0.57	0.7	ps (rms)	1,2,6
	$t_{jphPCIeG3}$	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.20	0.3	ps (rms)	1,2,4,6
	t_{jphQPI_SMI}	QPI & SMI (100MHz or 133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.22	0.3	ps (rms)	1,5,6
		QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.08	0.1	ps (rms)	1,5,6
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.08	0.1	ps (rms)	1,5,6

[1] Applies to all outputs.

[2] See http://www.pcisig.com for complete specs

[3] Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

[4] Subject to final ratification by PCI SIG.

[5] Calculated from Intel-supplied Clock Jitter Tool v 1.6.3

[6] For RMS figures, additive jitter is calculated by solving the following equation: (Additive jitter)^2 = (total jittter)^2 - (input jitter)^2

Clock Periods–Differential Outputs with Spread Spectrum Disabled

SSC OFF	Center Freq. MHz	Measurement Window							Units	Notes
		1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
		-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max		
DIF	100.00	9.94900		9.99900	10.00000	10.00100		10.05100	ns	1,2,3
	133.33	7.44925		7.49925	7.50000	7.50075		7.55075	ns	1,2,4

Clock Periods–Differential Outputs with Spread Spectrum Enabled

SSC ON	Center Freq. MHz	Measurement Window							Units	Notes
		1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
		-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max		
DIF	99.75	9.94906	9.99906	10.02406	10.02506	10.02607	10.05107	10.10107	ns	1,2,3
	133.00	7.44930	7.49930	7.51805	7.51880	7.51955	7.53830	7.58830	ns	1,2,4

Notes:

[1]Guaranteed by design and characterization, not 100% tested in production.

[2] All Long Term Accuracy specifications are guaranteed with the assumption that the input clock complies with CK420BQ/CK410B+ accuracy requirements (+/-100ppm). The 9ZX21501 itself does not contribute to ppm error.

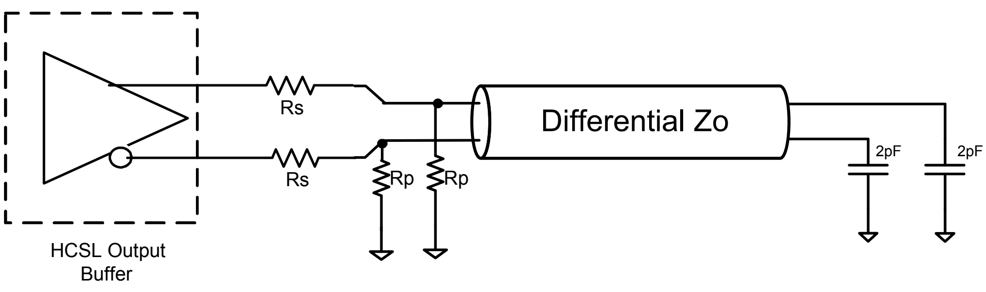
[3] Driven by SRC output of main clock, 100 MHz PLL Mode or Bypass mode

[4] Driven by CPU output of main clock, 133 MHz PLL Mode or Bypass mode

Differential Output Termination Table

DIF Zo (Ω)	Iref (Ω)	Rs (Ω)	Rp (Ω)
100	475	33	50
85	412	27	42.2 or 43.2

9ZX21501 Differential Test Loads



General SMBus Serial Interface Information for 9ZX21501B

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address $XX_{(H)}$
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) sends the byte count = X
- IDT clock will **acknowledge**
- Controller (host) starts sending Byte **N through Byte N+X-1**
- IDT clock will **acknowledg**e each byte **one at a time**
- Controller (host) sends a Stop bit

Index Block Write Operation			
Controller (Host)			IDT (Slave/Receiver)
T	starT bit		
Slave Address $XX_{(H)}$			
WR	WRite		
			ACK
Beginning Byte = N			
			ACK
Data Byte Count = X			
			ACK
Beginning Byte N		X Byte	
			ACK
O			
O			O
O			O
			O
Byte N + X - 1			
			ACK
P	stoP bit		

Note: $XX_{(H)}$ is defined by SMBus addess select pins.

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address $XX_{(H)}$
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) will send a separate start bit
- Controller (host) sends the read address $YY_{(H)}$
- IDT clock will **acknowledge**
- IDT clock will send the data byte count = X
- IDT clock sends Byte **N+X-1**
- IDT clock sends **Byte 0 through Byte X (if $X_{(H)}$ was written to Byte 8)**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Read Operation			
Controller (Host)			IDT (Slave/Receiver)
T	starT bit		
Slave Address $XX_{(H)}$			
WR	WRite		
			ACK
Beginning Byte = N			
			ACK
RT	Repeat starT		
Slave Address $YY_{(H)}$			
RD	ReaD		
			ACK
			Data Byte Count=X
ACK			
		X Byte	Beginning Byte N
ACK			
			O
O			O
O			O
O			
			Byte N + X - 1
N	Not acknowledge		
P	stoP bit		

SMBusTable: PLL Mode, and Frequency Select Register

Byte 0	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	3	PLL Mode 1	PLL Operating Mode Rd back 1	R	See PLL Operating Mode Readback Table		Latch
Bit 6	3	PLL Mode 0	PLL Operating Mode Rd back 0	R			Latch
Bit 5		Reserved					1
Bit 4	61/62	DIF_17_En	Output Control overrides OE# pin	RW	Hi-Z	Enable	1
Bit 3	58/59	DIF_16_En	Output Control overrides OE# pin	RW	Hi-Z	Enable	1
Bit 2		Reserved					0
Bit 1		Reserved					0
Bit 0	2	100M_133#	Frequency Select Readback	R	133MHz	100MHz	Latch

SMBusTable: Output Control Register

Byte 1	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	34/35	DIF_7_En	Output Control overrides OE# pin	RW	Hi-Z	Enable	1
Bit 6	31/32	DIF_6_En	Output Control overrides OE# pin	RW			1
Bit 5	28/29	DIF_5_En	Output Control overrides OE# pin	RW			1
Bit 4	25/26	DIF_4_En	Output Control overrides OE# pin	RW			1
Bit 3		Reserved					1
Bit 2	22/23	DIF_2_En	Output Control overrides OE# pin	RW	Hi-Z	Enable	1
Bit 1	20/21	DIF_1_En	Output Control overrides OE# pin	RW			1
Bit 0	17/18	DIF_0_En	Output Control overrides OE# pin	RW			1

SMBusTable: Output Control Register

Byte 2	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	56/57	DIF_15_En	Output Control overrides OE# pin	RW	Hi-Z	Enable	1
Bit 6		Reserved					1
Bit 5	53/54	DIF_13_En	Output Control overrides OE# pin	RW	Hi-Z	Enable	1
Bit 4	49/50	DIF_12_En	Output Control overrides OE# pin	RW			1
Bit 3	46/47	DIF_11_En	Output Control overrides OE# pin	RW			1
Bit 2	43/44	DIF_10_En	Output Control overrides OE# pin	RW			1
Bit 1		Reserved					1
Bit 0	37/38	DIF_8_En	Output Control overrides OE# pin	RW	Hi-Z	Enable	1

SMBusTable: Output Enable Pin Status Readback Register

Byte 3	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	51	OE_RB12	Real Time readback of OE#12	R	OE# pin Low	OE# Pin High	Real time
Bit 6	48	OE_RB11	Real Time readback of OE#11	R			Real time
Bit 5	45	OE_RB10	Real Time readback of OE#10	R			Real time
Bit 4		Reserved					0
Bit 3	39	OE_RB8	Real Time readback of OE#8	R	OE# pin Low	OE# Pin High	Real time
Bit 2	36	OE_RB7	Real Time readback of OE#7	R			Real time
Bit 1	33	OE_RB6	Real Time readback of OE#6	R			Real time
Bit 0	30	OE_RB5	Real Time readback of OE#5	R			Real time

SMBusTable: Reserved Register

Byte 4	Pin #	Name	Control Function	Type	0	1	Default
Bit 7		Reserved					0
Bit 6		Reserved					0
Bit 5		Reserved					0
Bit 4		Reserved					0
Bit 3		Reserved					0
Bit 2		Reserved					0
Bit 1		Reserved					0
Bit 0		Reserved					0

SMBusTable: Vendor & Revision ID Register

Byte 5	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	RID3	REVISION ID	R	B rev = 0001 C rev = 0010		X
Bit 6	-	RID2		R			X
Bit 5	-	RID1		R			X
Bit 4	-	RID0		R			X
Bit 3	-	VID3	VENDOR ID	R	-	-	0
Bit 2	-	VID2		R	-	-	0
Bit 1	-	VID1		R	-	-	0
Bit 0	-	VID0		R	-	-	1

SMBusTable: DEVICE ID

Byte 6	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	Device ID 7 (MSB)		R	Device ID is 219 decimal or DB hex.		1
Bit 6	-	Device ID 6		R			1
Bit 5	-	Device ID 5		R			0
Bit 4	-	Device ID 4		R			1
Bit 3	-	Device ID 3		R			1
Bit 2	-	Device ID 2		R			0
Bit 1	-	Device ID 1		R			1
Bit 0	-	Device ID 0		R			1

SMBusTable: Byte Count Register

Byte 7	Pin #	Name	Control Function	Type	0	1	Default
Bit 7		Reserved					0
Bit 6		Reserved					0
Bit 5		Reserved					0
Bit 4	-	BC4	Writing to this register configures how many bytes will be read back.	RW	Default value is 8 hex, so 9 bytes (0 to 8) will be read back by default.		0
Bit 3	-	BC3		RW			1
Bit 2	-	BC2		RW			0
Bit 1	-	BC1		RW			0
Bit 0	-	BC0		RW			0

SMBusTable: Reserved Register

Byte 8	Pin #	Name	Control Function	Type	0	1	Default
Bit 7		Reserved					0
Bit 6		Reserved					0
Bit 5		Reserved					0
Bit 4		Reserved					0
Bit 3		Reserved					0
Bit 2		Reserved					0
Bit 1		Reserved					0
Bit 0		Reserved					0

DIF Reference Clock			
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1
Rs	33	ohm	1
Rt	49.9	ohm	1

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2

Figure 1: Down Device Routing

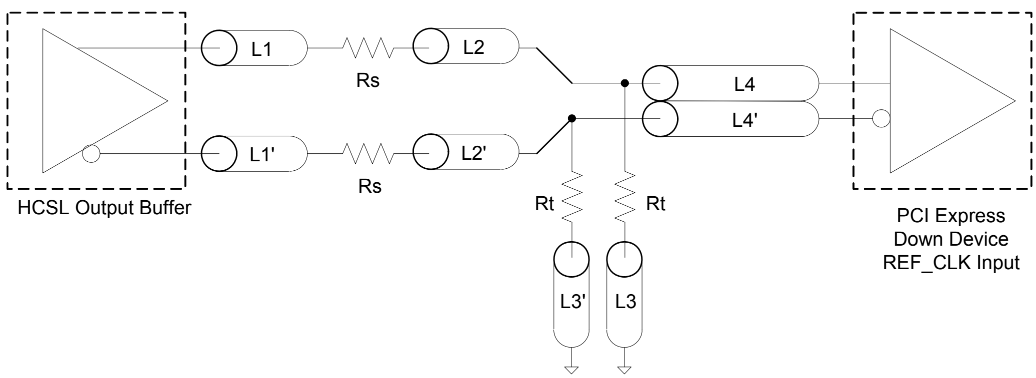
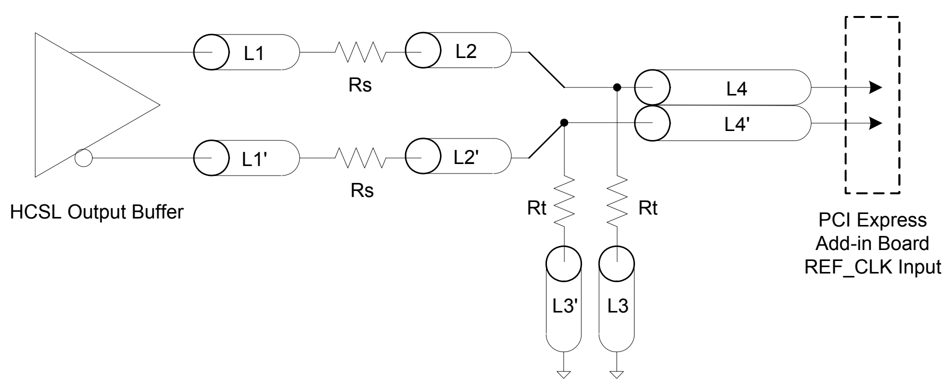


Figure 2: PCI Express Connector Routing

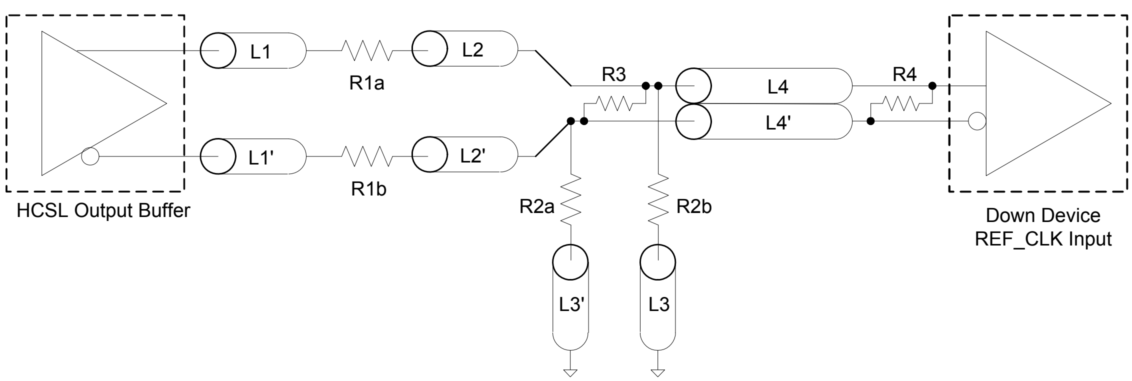


Alternative Termination for LVDS and other Common Differential Signals (figure 3)							
Vdiff	Vp-p	Vcm	R1	R2	R3	R4	Note
0.45v	0.22v	1.08	33	150	100	100	
0.58	0.28	0.6	33	78.7	137	100	
0.80	0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible
0.60	0.3	1.2	33	174	140	100	Standard LVDS

R1a = R1b = R1

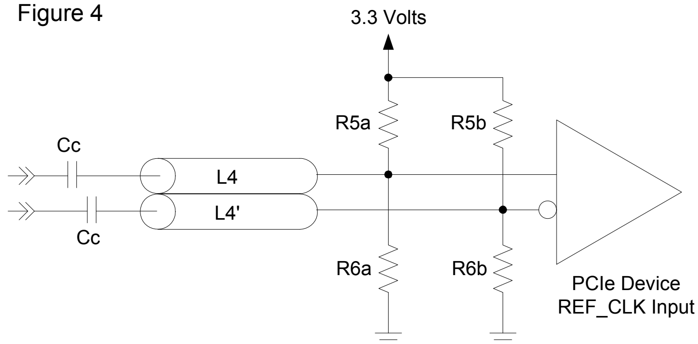
R2a = R2b = R2

Figure 3

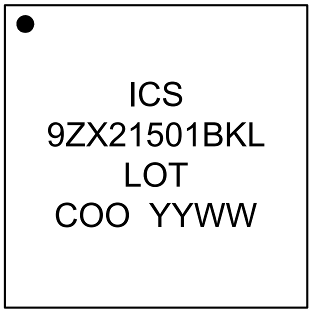


Cable Connected AC Coupled Application (figure 4)		
Component	Value	Note
R5a, R5b	8.2K 5%	
R6a, R6b	1K 5%	
Cc	0.1 µF	
Vcm	0.350 volts	

Figure 4



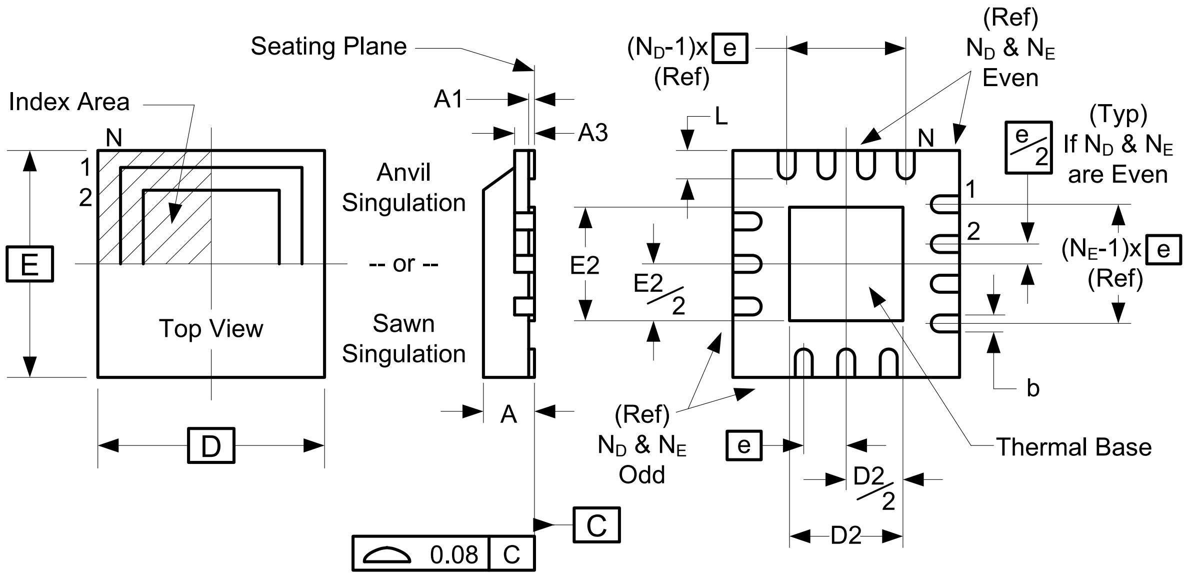
Marking Diagram



Notes:

1. “LOT” is the lot number.
2. “COO” is the country of origin.
3. YYWW is the last two digits of the year and week that the part was assembled.
4. “L” denotes RoHS compliant package.

Package Outline and Package Dimensions (64-pin MLF)



	Millimeters	
Symbol	**Min**	**Max**
A	0.8	1.0
A1	0	0.05
A3	0.25 Reference	
b	0.18	0.3
e	0.50 BASIC	
D x E BASIC	9.00 x 9.00	
D2 MIN./MAX.	6.00	6.25
E2 MIN./MAX.	6.00	6.25
L MIN./MAX.	0.30	0.50
N_D	16	
N_E	16	
N	64	

Ordering Information

Part / Order Number	Shipping Package	Package	Temperature
9ZX21501BKLF	Trays	64-pin MLF	0 to +70°C
9ZX21501BKLFT	Tape and Reel	64-pin MLF	0 to +70°C

"LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

“B” is the device revision designator (will not correlate with the datasheet revision).

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Revision History

Rev.	Issue Date	Who	Description	Page #
A	8/5/2010	RDW	Move to final.	
B	12/8/2011	RDW	1. Updated tDSPO_BYP parameter from +/-350 to +/-250ps	7
C	12/15/2011	RDW	1. Lowered IDD3.3OP from MAX 500mA/TYP 407mA to MAX 425mA/ TYP 390mA 2. Lowered IDD3.3PDZ from MAX36mA/TYP 12mA to MAX 15mA/ TYP 5mA	8
D	4/23/2012	RDW	1. Updated Rp values on Output Terminations Table from 43.2 ohms to 42.2 or 43.2 ohms to be consistent with Intel.	9
E	4/16/2013	RDW	Corrected typo in OE# Latency parameter; changed 1 min. to 3 max. cycles to 4 min. to 12 max. clocks	6

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